

IN THE CLAIMS:

Please amend the claims as follows:

1. (Once Amended) A method of making an IC chip package having an IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with the IC chip, the IC chip being mounted upon a substrate, the method comprising:

providing a container disposed upon the substrate; and

injecting a grease in contact with the active surface of the IC chip such that the grease is:

enclosed by the container and the substrate; and

is in contact with the active surface and the electrical connector.

12. (Once Amended) A method of making an IC chip package having a flip chip with an inactive surface and an active surface, the active surface having extending therefrom an electrical connector in electrical communication with the flip chip, the flip chip being mounted upon a substrate, the method comprising:

providing a container disposed upon the substrate and in contact with the inactive surface of the flip chip; and

injecting a grease between the container and the substrate so as to contact the active surface of the flip chip, wherein:

the grease is in contact with the active surface and the electrical connector.

18. (Once Amended) The method as defined in Claim 17, further comprising:

operating the first, second, and third IC chips to generate heat therefrom; and

conducting the heat from the electrical connector and from the first, second, and third IC chips to the grease, to the container, and to the ambient.